

SOT1051-1

plastic thin fine-pitch ball grid array package; 273 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA273
Package type industry code	TFBGA273
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-195
Mounting method type	S (surface mount)
Issue date	14-11-2007

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	9.9	-	10	10.1	mm
E	package width	9.9	-	10	10.1	mm
A	seated height	[tbd]	-	1.1	1.1	mm
A ₂	package height	0.65	-	0.725	0.8	mm
n ₂	actual quantity of termination	-	-	273	-	



2. Package outline

TFBGA273: plastic thin fine-pitch ball grid array package; 273 balls SOT1051-1

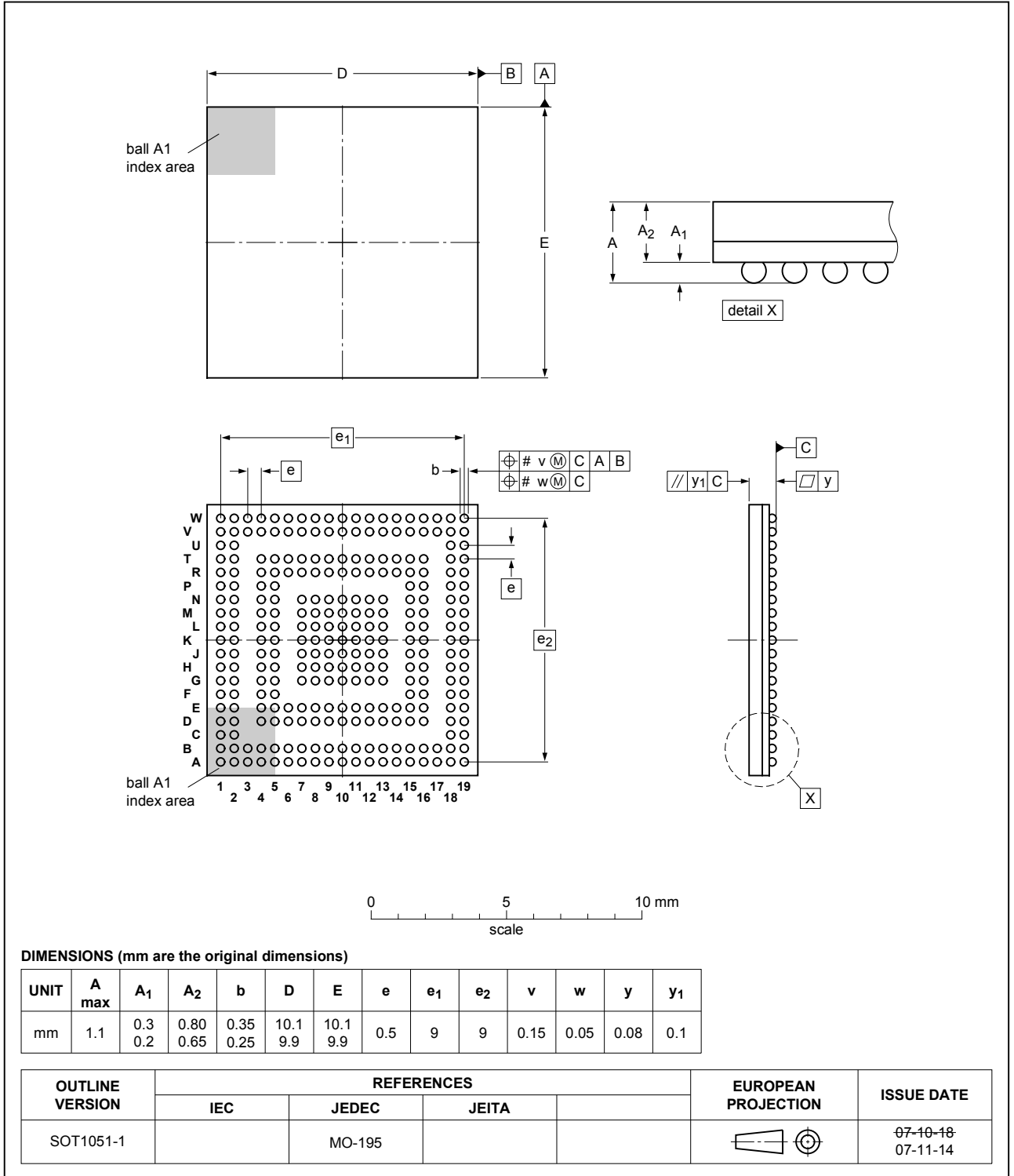


Fig. 1. Package outline TFBGA273 (SOT1051-1)

3. Soldering

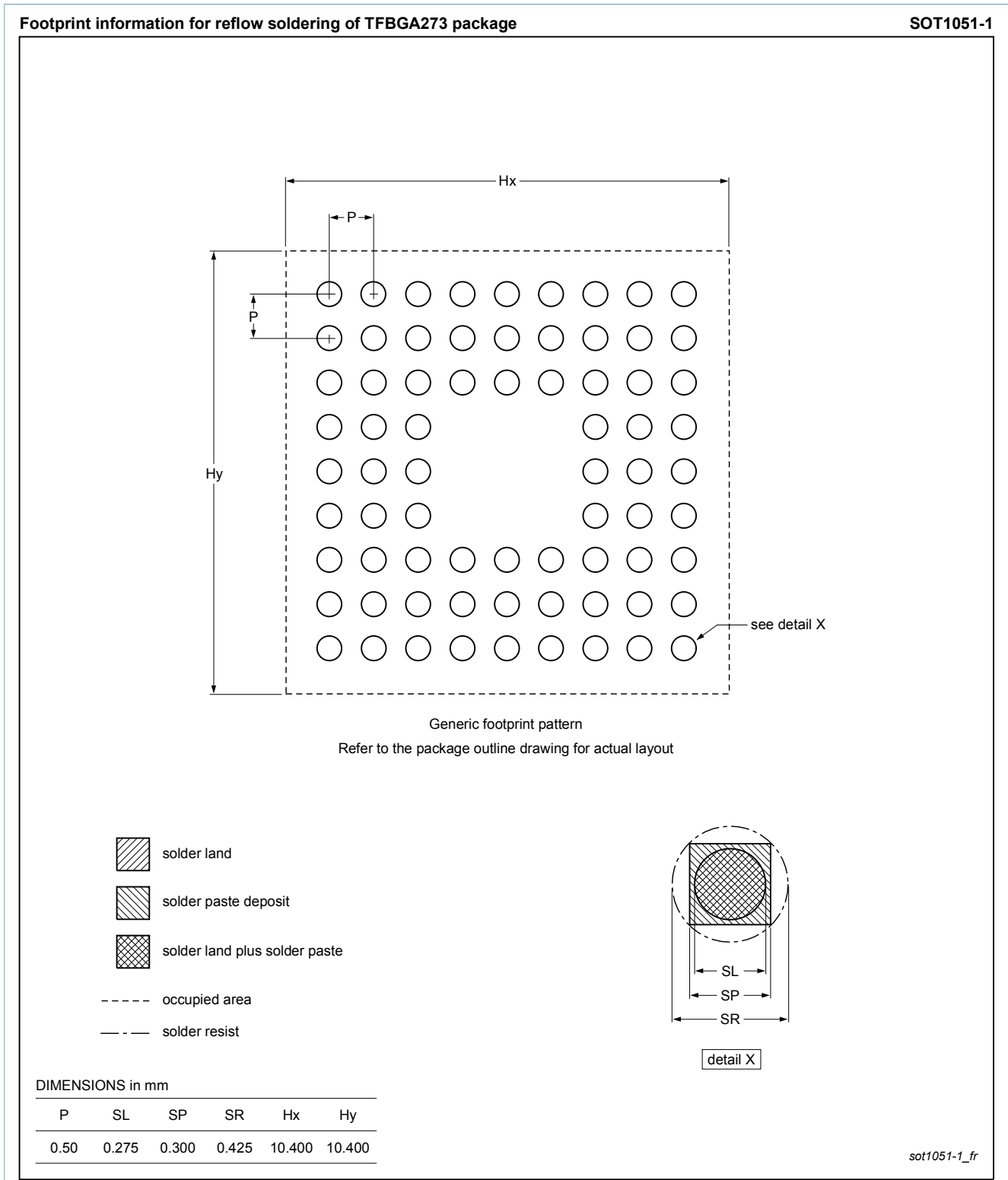


Fig. 2. Reflow soldering footprint for TFBGA273 (SOT1051-1)

4. Legal information

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